

Features

- High Density Cell Design For Low $R_{DS(ON)}$
- Voltage Controlled Small Signal Switch
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device ⁽¹⁾
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

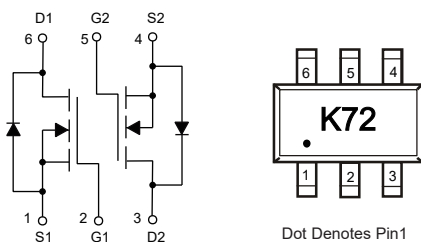
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 415°C/W Junction to Ambient(Steady-State)⁽²⁾

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	340
		$T_A=100^\circ\text{C}$	215
Pulsed Drain Current ⁽³⁾	I_{DM}	1.36	A
Total Power Dissipation ⁽⁴⁾	P_D	300	mW

Note:

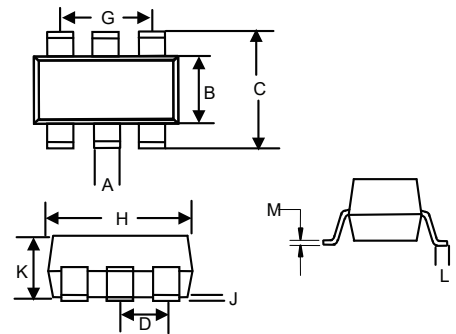
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA} t \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction to ambient thermal resistance.

Internal Structure and Marking Code



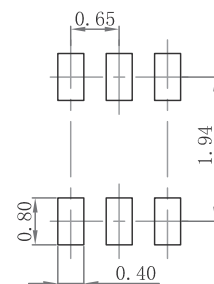
DUAL N-CHANNEL MOSFET

SOT-363



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.006	0.014	0.15	0.35	
B	0.045	0.053	1.15	1.35	
C	0.079	0.096	2.00	2.45	
D	0.026		0.65		TYP.
G	0.047	0.055	1.20	1.40	
H	0.071	0.087	1.80	2.20	
J	-----	0.004	-----	0.10	
K	0.031	0.043	0.80	1.10	
L	0.010	0.018	0.26	0.46	
M	0.003	0.006	0.08	0.15	

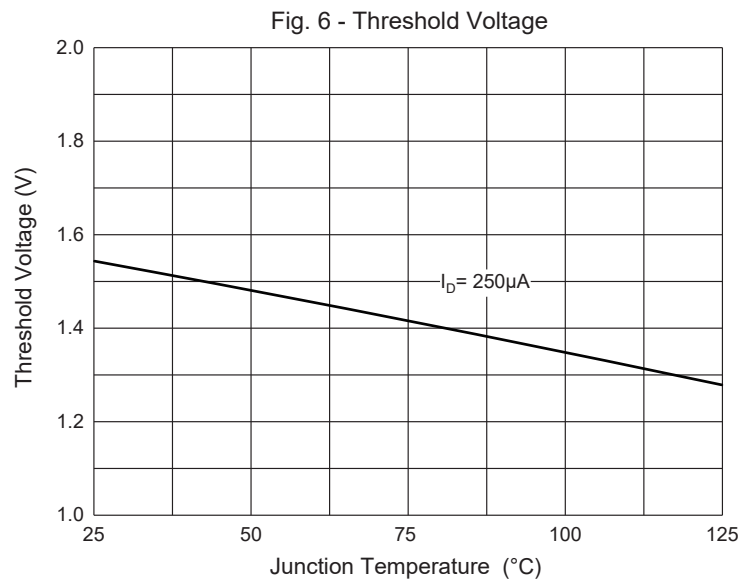
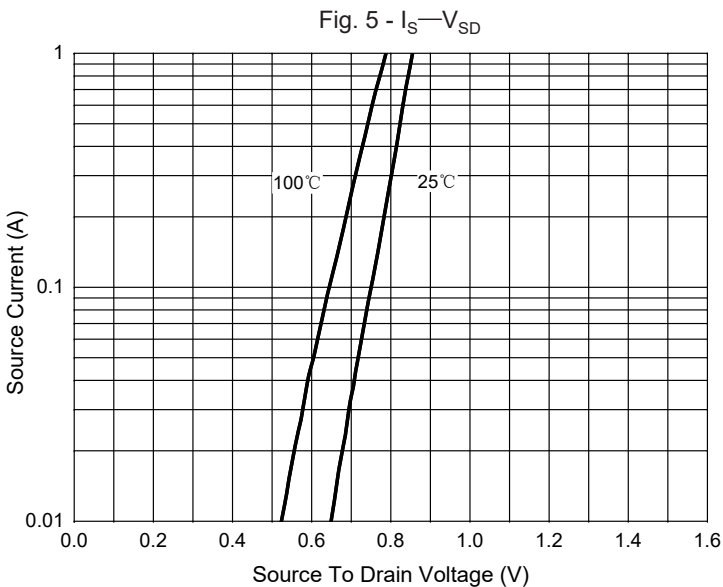
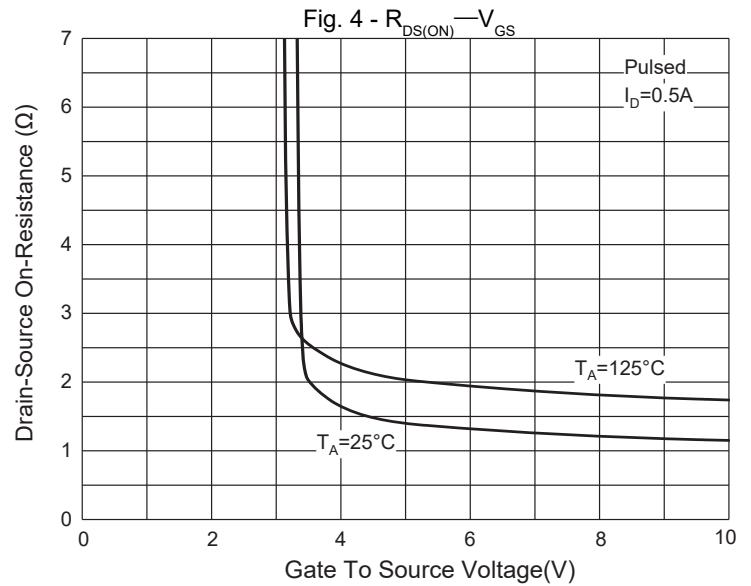
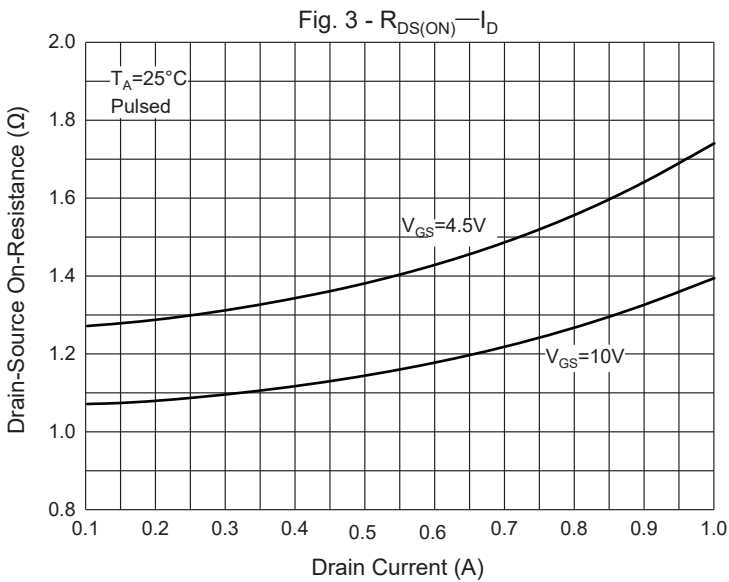
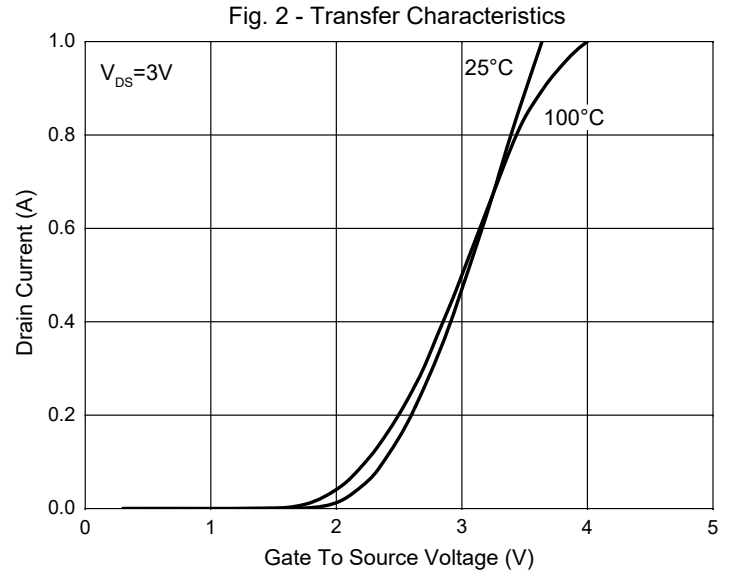
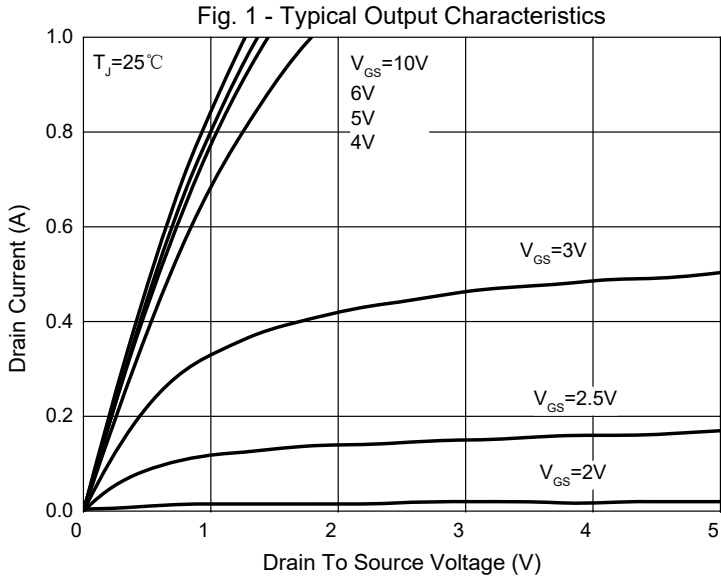
SUGGESTED SOLDER PAD LAYOUT



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	60			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 10	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$			80	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=300mA$		1.1	2.5	Ω
		$V_{GS}=4.5V, I_D=200mA$		1.3	3	
Forward Transconductance	g_{fs}	$V_{DS}=10V, I_D=200mA$	80			ms
Gate Resistance	R_g	F=1 MHz, Open drain		4.1		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				115	mA
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=115mA$	0.55		1.2	V
Reverse Recovery Time	t_{rr}	$I_F=0.5A, dI_F/dt=100A/\mu s$		9.4		ns
Reverse Recovery Charge	Q_{rr}				3.1	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		25.2		pF
Output Capacitance	C_{oss}			3.5		
Reverse Transfer Capacitance	C_{rss}			2.2		
Total Gate Charge	Q_g	$V_{DS}=25V, V_{GS}=10V, I_D=0.5A$		1.1		nC
Gate-Source Charge	Q_{gs}			0.19		
Gate-Drain Charge	Q_{gd}			0.25		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=25V, V_{GEN}=10V, R_{GEN}=25\Omega, I_{DS}=500mA$		2.3		ns
Turn-On Rise Time	t_r			2.7		
Turn-Off Delay Time	$t_{d(off)}$			6.3		
Turn-Off Fall Time	t_f			3		

Curve Characteristics



Curve Characteristics

Fig.7-NormalizedOnResistanceCharacteristics

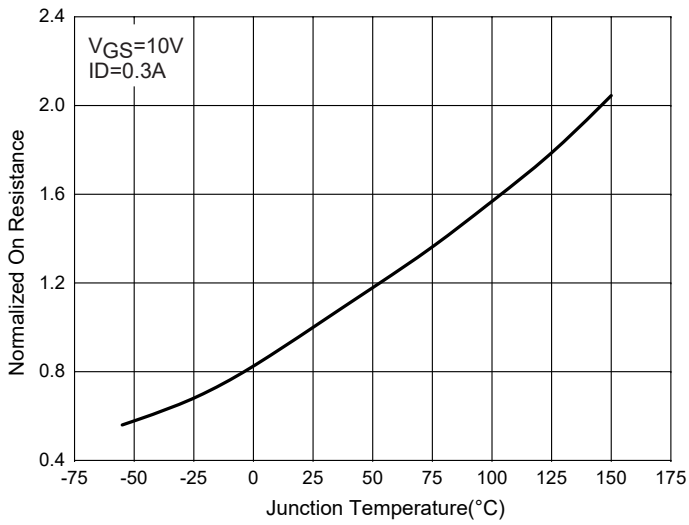


Fig. 8 - GateCharge

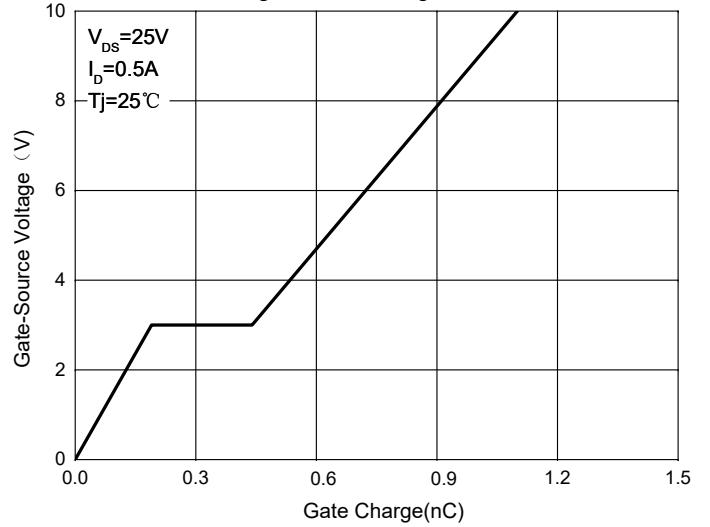


Fig. 9 - Capacitance Characteristics

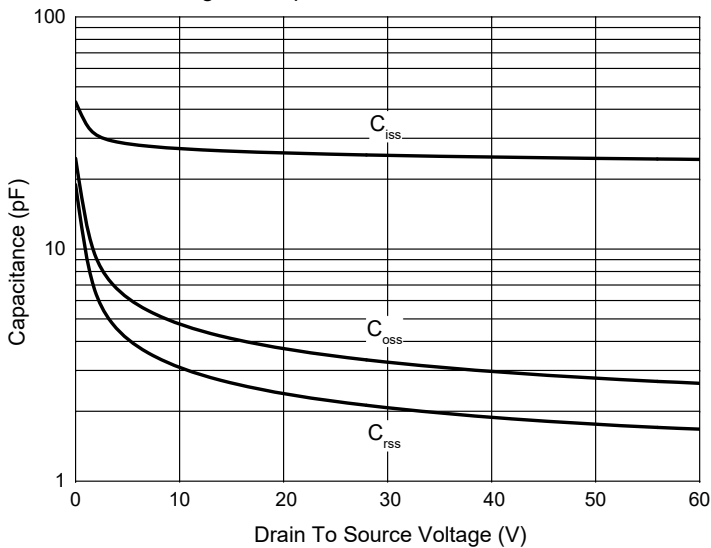


Fig. 10 - Current dissipation

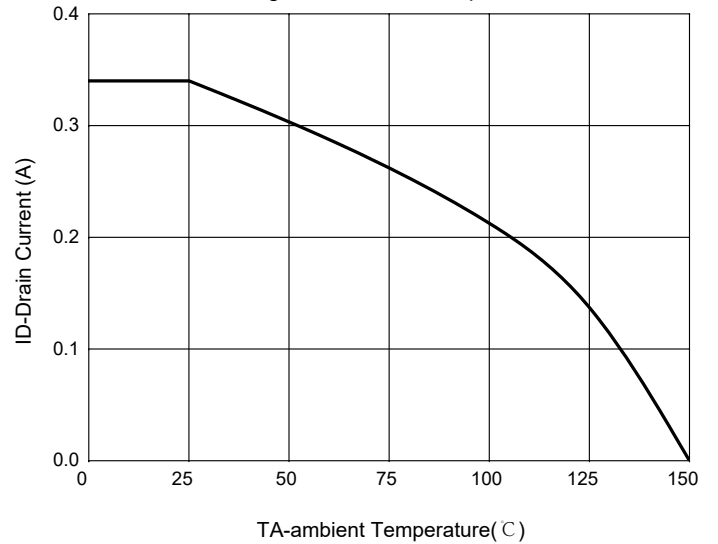
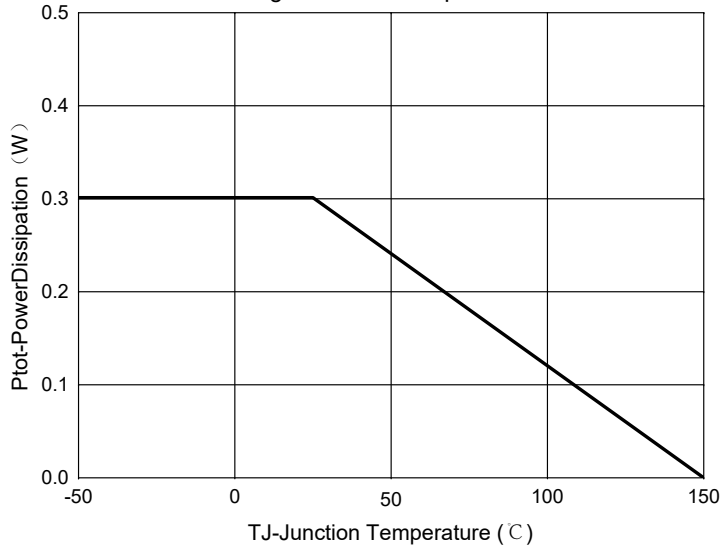


Fig.11-PowerDissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

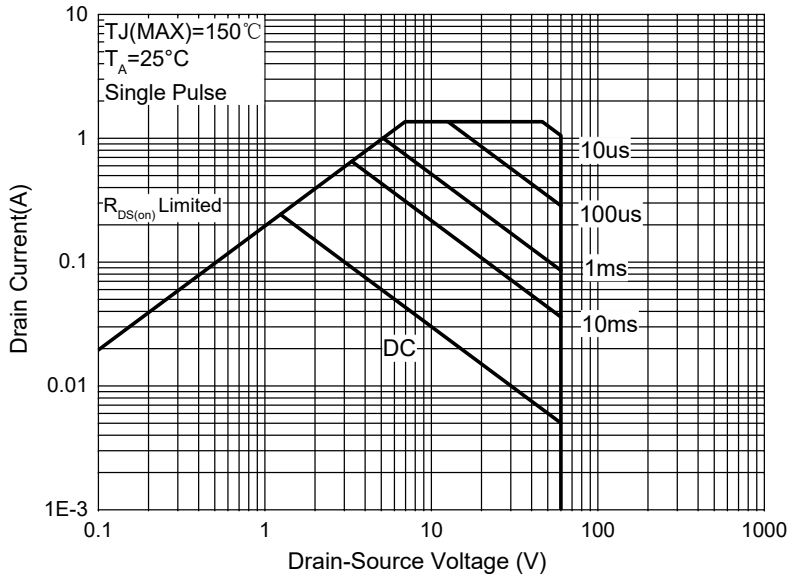
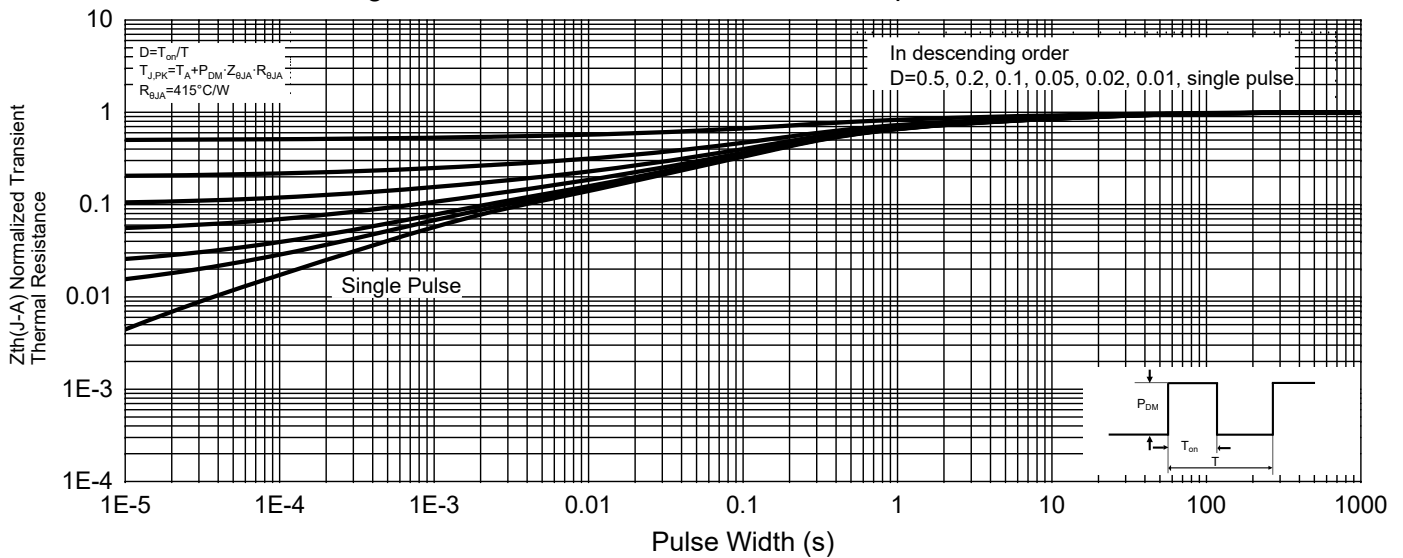


Fig. 13 -Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
2N7002DW-TP	Tape&Reel: 3Kpcs/Reel

Revision History

Datasheet status	Version No	Release date	Update content
New product datasheet	Rev4-1	20221214	

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